L Number	Hits	Search Text	DB	Time stamp
1	3973	324/765-769.ccls.	USPAT;	2002/07/24 11:43
			US-PGPUB;	
		•	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
8	269	324/765-769.ccls. and spring	USPAT;	2002/07/24 11:43
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
		(00 (705 700)	IBM_TDB	0000/07/04 44:44
15	199	(324/765-769.ccls. and spring) and (ball bead bump lead)	USPAT;	2002/07/24 11:44
			US-PGPUB;	
	;	A	EPO; JPO;	
			DERWENT;	
00	7540	(hall hown hand) near@ (contact\$2 connect\$2) near@ enring	IBM_TDB USPAT;	2002/07/24 13:34
22	7542	(ball bump bead) near8 (contact\$3 connect\$3) near8 spring	US-PGPUB:	2002/01/24 13.34
			EPO; JPO;	
			DERWENT:	
			IBM_TDB	
29	127	((ball bump bead) near8 (contact\$3 connect\$3) near8 spring)	USPAT:	2002/07/24 13:33
25	'2'	and BGA	US-PGPUB;	2002.07721 10100
			EPO; JPO;	
		*	DERWENT;	
			IBM_TDB	
36	2230	(ball bump bead) near3 (contact\$3 connect\$3) near3 spring	USPAT;	2002/07/24 14:53
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
43	270338	(opening hole via socket) near20 spring	USPAT;	2002/07/24 14:17
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	0000/07/04 44 00
50	945	((ball bump bead) near3 (contact\$3 connect\$3) near3 spring)	USPAT;	2002/07/24 14:20
		and ((opening hole via socket) near20 spring)	US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM_TDB	
57	282	((ball bump bead) near3 (contact\$3 connect\$3) near3 spring)	USPAT;	2002/07/24 14:27
37	202	near20 (portion part)	US-PGPUB;	2002/01/24 14.27
		House (politon part)	EPO; JPO;	
			DERWENT:	
			IBM_TDB	
64	24	(((ball bump bead) near3 (contact\$3 connect\$3) near3	USPAT;	2002/07/24 14:28
		spring) and ((opening hole via socket) near20 spring)) and	US-PGPUB;	
		bga	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
71	430	(ball bump bead) near3 (contact\$3 connect\$3) near3 (coil	USPAT;	2002/07/24 14:55
		helix helical spiral)	US-PGPUB;	
			EPO; JPO;	
		*	DERWENT;	
	_	(4) 11.1	IBM_TDB	2002/07/24 45:54
78	8	((ball bump bead) near3 (contact\$3 connect\$3) near3 (coil	USPAT;	2002/07/24 15:54
		helix helical spiral)) and bga	US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM_TDB	
l	1		IDM IDD	

85	3	5854558.pn.	USPAT;	2002/07/24 14:57
			US-PGPUB;	
			EPO; JPO;	
1		•	DERWENT;	
			IBM_TDB	
92	2	6229320.pn.	USPAT;	2002/07/24 14:58
32	_	0220020.pm	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
99	11947	fill\$3 near3 (hole via groove socket) near10 (conduct\$3)	USPAT;	2002/07/24 16:26
			US-PGPUB;	
			EPO; JPO;	
		.	DERWENT;	
			IBM_TDB	
106	169	((opening hole via socket) near20 spring) and (fill\$3 near3	USPAT;	2002/07/24 16:13
		(hole via groove socket) near10 (conduct\$3))	US-PGPUB;	
1		· · · · · · · · · · · · · · · · · · ·	EPO; JPO;	
}			DERWENT;	
			IBM_TDB	
113	23	((opening hole via socket) near20 spring) same (fill\$3 near3	USPAT;	2002/07/24 16:11
		(hole via groove socket) near10 (conduct\$3))	US-PGPUB;	
			EPO; JPO;	
		A	DERWENT;	
			IBM_TDB	
120	0	((ball bump bead) near3 (contact\$3 connect\$3) near3 (coil	USPAT;	2002/07/24 16:12
		helix helical spiral)) same (fill\$3 near3 (hole via groove	US-PGPUB;	
		socket) near10 (conduct\$3))	EPO; JPO;	
			DERWENT;	
		(44 NA	IBM_TDB	0000/07/04 46:40
127	1	((ball bump bead) near3 (contact\$3 connect\$3) near3 (coil	USPAT;	2002/07/24 16:12
		helix helical spiral)) and (fill\$3 near3 (hole via groove socket)	US-PGPUB;	
		near10 (conduct\$3))	EPO; JPO;	
		•	DERWENT;	
124	20	///ananing halo via conket) near20 enring \ and /fill\$2 near2	IBM_TDB USPAT;	2002/07/24 16:15
134	29	(((opening hole via socket) near20 spring) and (fill\$3 near3 (hole via groove socket) near10 (conduct\$3))) and (PCB	US-PGPUB;	2002/01/24 10.15
			EPO; JPO;	
		PWB BGA)	DERWENT;	
			IBM_TDB	
141	3	5,366,380.pn.	USPAT;	2002/07/24 16:15
1-7		0,000,000.pm. -	US-PGPUB;	
			EPO; JPO;	
			DERWENT:	
		•	IBM_TDB	
148	161	(hole via groove socket) near10 (conduct\$3 solder paste)	USPAT;	2002/07/24 16:56
' ' -		near10 ((hold\$3 bond\$3) near3 (spring coil helix helical	US-PGPUB;	
		spiral))	EPO; JPO;	
		' ''	DERWENT;	
			IBM_TDB	